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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/099,900	03/14/2002	Ronald Vern Schauer	004448 USA P 02/CPS/IBSS	3672

32588 7590 08/02/2004

APPLIED MATERIALS, INC.
2881 SCOTT BLVD. M/S 2061
SANTA CLARA, CA 95050

EXAMINER

MORRISON, NASCHICA SANDERS

ART UNIT	PAPER NUMBER
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3632

DATE MAILED: 08/02/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

Interview Summary

Application No.

10/099,900

Applicant(s)

SCHAUER, RONALD VERN

Examiner

Naschica S Morrison

Art Unit

3632

All participants (applicant, applicant's representative, PTO personnel):

(1) Naschica S Morrison.

(3) _____.

(2) Brian Dugan.

(4) _____.

Date of Interview: 28 July 2004.

Type: a) ☒ Telephonic b) ☐ Video Conference
c) ☐ Personal [copy given to: 1) ☐ applicant 2) ☐ applicant's representative]

Exhibit shown or demonstration conducted: d) ☐ Yes e) ☒ No.

If Yes, brief description: _____.

Claim(s) discussed: 1,17-21 and 23.

Identification of prior art discussed: None.

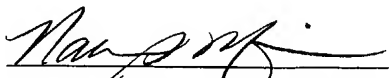
Agreement with respect to the claims f) ☐ was reached. g) ☒ was not reached. h) ☐ N/A.

Substance of Interview including description of the general nature of what was agreed to if an agreement was reached, or any other comments: Applicant provided proposed claim amendments (see attached copy of fax dated 7/28/04) for review by examiner. Examiner stated that the proposed limitation beginning "so that the box..." would be considered a functional limitation and would not likely negate the existing rejections since it would only require that the mounting mechanism of the prior art be capable of performing the function.

(A fuller description, if necessary, and a copy of the amendments which the examiner agreed would render the claims allowable, if available, must be attached. Also, where no copy of the amendments that would render the claims allowable is available, a summary thereof must be attached.)

THE FORMAL WRITTEN REPLY TO THE LAST OFFICE ACTION MUST INCLUDE THE SUBSTANCE OF THE INTERVIEW. (See MPEP Section 713.04). If a reply to the last Office action has already been filed, APPLICANT IS GIVEN ONE MONTH FROM THIS INTERVIEW DATE, OR THE MAILING DATE OF THIS INTERVIEW SUMMARY FORM, WHICHEVER IS LATER, TO FILE A STATEMENT OF THE SUBSTANCE OF THE INTERVIEW. See Summary of Record of Interview requirements on reverse side or on attached sheet.

Examiner Note: You must sign this form unless it is an Attachment to a signed Office action.


Examiner's signature, if required

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FACSIMILE COVER SHEET

July 28, 2004

PLEASE DELIVER THE ATTACHED MESSAGE TO:

Examiner: Naschica S. Morrison Phone No.: (703) 305-0228
From: Brian M. Dugan Fax No.: (703) 746-3991

Our File No.: Docket No. 4448/P2/CPS/IBSS/LAP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Ronald Vern Schauer and John Charles
Davies
Serial No. : 10/099,900
Filed : March 14, 2002
For : FACILITIES CONNECTION BUCKET FOR PRE-
FACILITATION OF WAFER FABRICATION
EQUIPMENT
Examiner : Naschica S. Morrison
Group Art Unit : 3632

TOTAL NUMBER OF PAGES INCLUDING THIS PAGE: 5

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Serial No. 10/099,900

Docket No. 4448/P2/CPS/IBSS/LAP

Proposed Claim Amendments

Claim 1 (Currently Amended): A standardized facilities box comprising:

a box;

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal; and

one or more mechanisms for selectively coupling any one of a set of add-on features within the box.

Claim 2 (Original): The standardized facilities box of claim 1 further comprising an add-on feature coupled to the one or more mechanisms for selectively coupling.

Claim 3 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a partition.

Claim 4 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a document storage compartment.

Claim 5 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a sensor and a warning indicator.

Claim 6 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises an automatic lockout mechanism.

Claim 7 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a tool storage mechanism.

Claims 8-9 (Canceled).

Claim 10 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a mechanical locating mechanism for a facilities connection.

Claim 11 (Canceled).

Claim 12 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises an openable cover.

Claim 13 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises floor lighting.

Claim 14 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a lifting mechanism adapted to lift and/or lower the box into or from a position for mounting the box to a support pedestal.

Claim 15 (Original): The standardized facilities box of claim 2 wherein the add-on feature comprises a lifting mechanism adapted to lift and/or lower an item to or from the box.

Claim 16 (Canceled).

**Claim 17 (Currently Amended): A facilities box comprising:
a box adapted to house facilities connections therein;**

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal; and

a lifting mechanism coupled to the box adapted to lift and/or lower the box into or from a position for mounting the box to a the support pedestal.

Claim 18 (Currently Amended): A facilities box comprising:

a box adapted to house facilities connections therein;

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal; and

a lifting mechanism adapted to lift and/or lower an item to or from the box.

Claim 19 (Currently Amended): A facilities box comprising:

a box adapted to house facilities connections therein;

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal; and

a sensor.

Claim 20 (Currently Amended): A facilities box comprising:

a box adapted to house facilities connections therein;

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal; and

an exhaust mechanism.

Claim 21 (Currently Amended): A facilities box comprising:

a box adapted to house facilities connections therein;

a mechanism for mounting the box to a support pedestal of a semiconductor fabrication facility so that the box is located outside of a perimeter of the support pedestal;

a cover coupled to the box; and

a lockout mechanism adapted to lock the cover of the box.

Claim 22 (Original): The facilities box of claim 21 wherein the lockout mechanism is a lockout tag out mechanism.

Claim 23 (Currently Amended): A method of standardizing a semiconductor fabrication facility, comprising:

indicating a location within a fabrication facility for installing a facilities box;

providing a standardized facilities box having a mechanism for selectively coupling any one of a set of add-on features to the standardized facilities box, the facilities box being adapted to be mounted to a support pedestal of a semiconductor fabrication facility so that the facilities box is located outside of a perimeter of the support pedestal;

providing a plurality of add-on features; and

specifying which add-on feature should be selectively coupled to which selective coupling mechanism of the standardized facilities box.